



Click [here](#) for the 3D model.

Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	2.5mm +/-0.20mm
B	0.6mm +/-0.35mm

  

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	390 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	2200 pF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	2500 VDC
Dielectric Withstanding Voltage	3000 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.